

TEFC1-01212P-TTAu-T200-AIN

General Description

The 12 couples, 3.0/2.4 mm \times 1.6mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 °C, designed for superior cooling and heating up to 200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

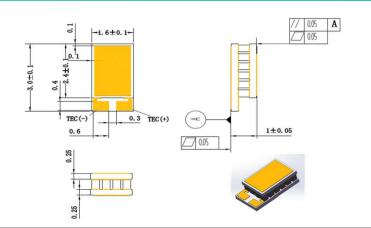
Applications

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (⁰C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	1.58	1.70	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	1.2	1.2	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	1.19	1.28	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	0.99	1.07	The module resistance is tested under AC	
Tolerance (%)	10%		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



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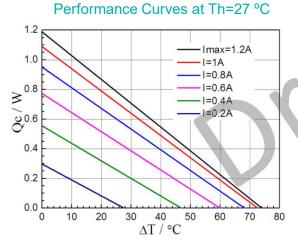
Thermoelectric Module

Manufacturing Options

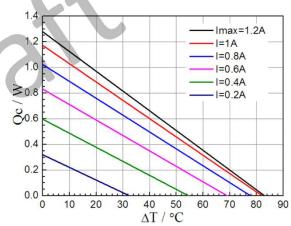
A. Solder: T200: CuSn (Tmelt=227°C) B. Sealant: NS: No sealing C. Ceramics: Aluminum Nitride (AIN) D. Ceramics Surface Options: Hot side: Metalized (Au plating) Cold side: Metalized (Au plating)

Ordering Option

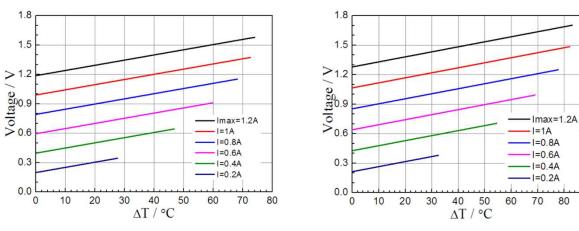
Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:1.0± 0.05	0: 0.05/0.05	No Wires



Performance Curves at Th=50 °C







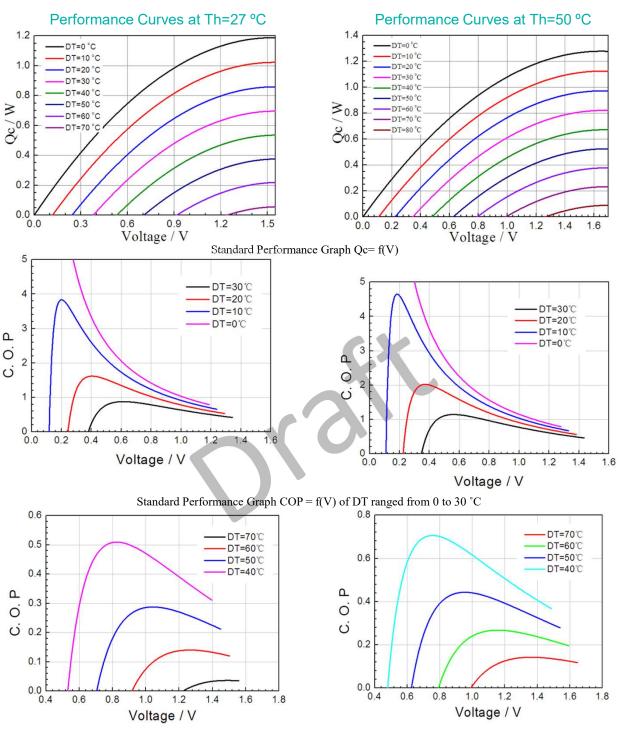
Standard Performance Graph V= f(DT)



90



Thermoelectric Module



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V \times I).

Operation Caution

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below Imax or Vmax
- Work under DC

Note: All specifications subject to change without notice.

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